



N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)}	Package	I _D T _C = 25°C
650V	3.0 Ω@V _{GS} = 10V	TO220-3	4.0 A

Description

This new generation complementary MOSFET features low onresistance and fast switching, making it ideal for high efficiency power management applications.

Applications

- Motor control
- Backlighting
- DC-DC Converters
- · Power management functions

Features

- Low Input Capacitance
- High BVDss rating for power application
- Low Input/Output Leakage
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

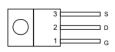
Mechanical Data

- Case: TO220-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish-Matte Tin annealed over Copper Leadframe Solderable per MIL-STD-202, Method 208 (€3)
- Terminal Connections: See Diagram Below
- Weight: 0.008 grams (approximate)

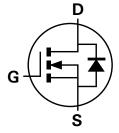
TO220-3



Top View



Top View Pin Out Configuration



Equivalent Circuit

Ordering Information (Note 4)

-			
	Part Number	Case	Packaging
١	DMG4N65CT	TO220-3	50 pieces/tube

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.

Marking Information



4N65CT = Product Type Marking Code YYWW = Date Code Marking YY = Last two digits of year (ex: 12 = 2012) WW = Week (01 - 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	650	V
Gate-Source Voltage			V_{GSS}	±30	V
Continuous Drain Current (Note 5) V _{GS} = 10V	Steady State	T _C = +25°C T _C = +70°C	I _D	4.0 3.0	А
Pulsed Drain Current (Note 7)			I _{DM}	6	A
Avalanche Current (Note 8) V _{DD} = 100V, V _{GS} = 10V, L = 60mH			I _{AS}	3.9	A
Repetitive avalanche energy (Note 7)			Eas	456	mJ

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Power Dissipation (Note 5)	P_{D}	2.19	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 5)	$R_{\theta JA}$	58.5	°C/W
Power Dissipation (Note 6)	P_{D}	9.14	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 6)	$R_{\theta JA}$	2.85	°C/W
Thermal Resistance, Junction to Case @T _A = +25°C (Note 6)	$R_{\theta JC}$	0.86	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

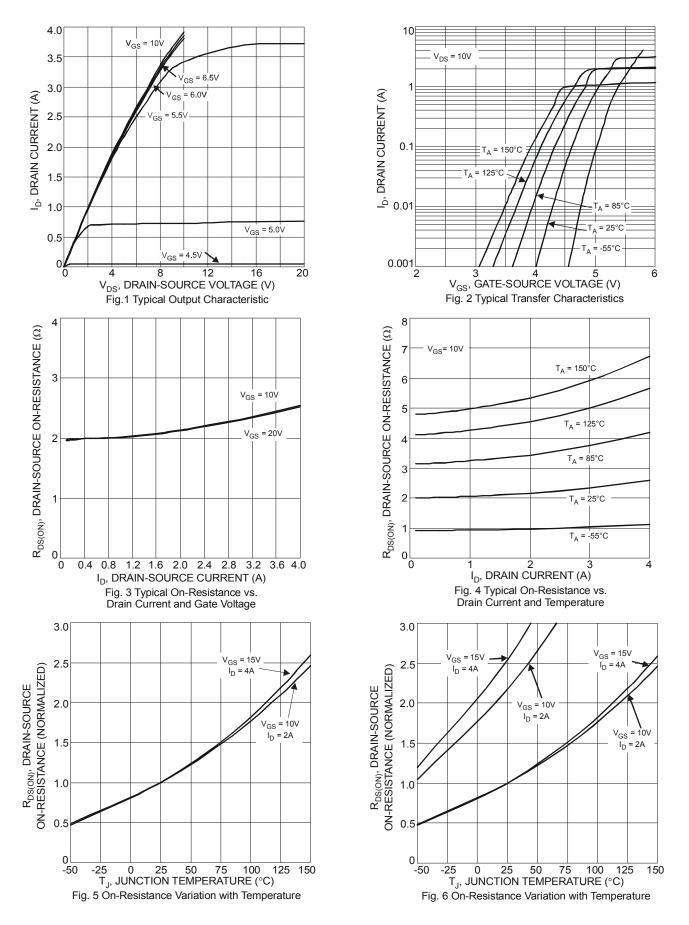
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV_{DSS}	650	-	-	٧	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T _J = 25°C	I _{DSS}	-	-	1.0	μΑ	V _{DS} = 650V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	1	-	±100	nA	$V_{GS} = \pm 30V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	$V_{GS(th)}$	3	-	5	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance	R _{DS (ON)}	-	2.1	3.0	Ω	$V_{GS} = 10V, I_D = 2A$	
Forward Transfer Admittance	Y _{fs}	-	3.7	-	S	$V_{DS} = 40V, I_{D} = 2A$	
Diode Forward Voltage	V_{SD}	-	0.7	1.0	V	$V_{GS} = 0V$, $I_S = 1A$	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	C _{iss}	1	900	-	pF	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz	
Output Capacitance	Coss	-	50	-			
Reverse Transfer Capacitance	C _{rss}	_	1.1	-			
Gate Resistance	R_g	-	2.4	-	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge V _{GS} = 10V	Q_g	-	13.5	-		V - 40V V - 500V	
Gate-Source Charge	Q_{gs}	-	2.7	-	nC	$V_{GS} = 10V, V_{DS} = 520V,$ $I_{D} = 4A$	
Gate-Drain Charge	Q_{gd}	-	3.8	-		ID - 4A	
Turn-On Delay Time	t _{D(on)}	-	15.1	-	ns	V _{GS} = 10V, V _{DS} = 325V,	
Turn-On Rise Time	t _r	-	13.8	-	ns		
Turn-Off Delay Time	t _{D(off)}	-	40	-	ns	$R_G = 25\Omega, I_D = 4A$	
Turn-Off Fall Time	t _f	-	16	-	ns	7	
Body Diode Reverse Recovery Time	t _{rr}	-	515	-	ns	dl/dt = 100A/μs, V _{DS} = 100V,	
Body Diode Reverse Recovery Charge	Q _{rr}	-	2330	-	nC	I _F = 4A	

Notes:

- 5. Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
- Device mounted on an infinite heatsink
 Repetitive rating, pulse width limited by junction temperature.
- 8. las and Eas rating are based on low frequency and duty cycles to keep T_J = +25°C. 9. Short duration pulse test used to minimize self-heating effect.
- 10. Guaranteed by design. Not subject to production testing.





T_A = 25°C



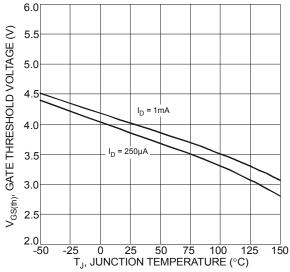


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

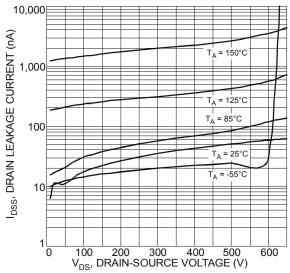
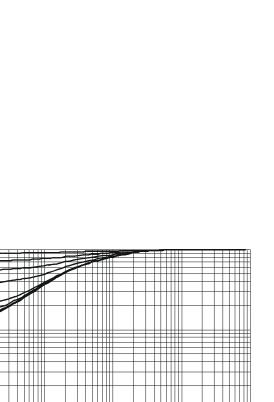


Fig. 9 Typical Drain-Source Leakage Current vs. Voltage



UNATURE D = 0.5 | D = 0.5 | D = 0.05 | D = 0.05 | D = 0.005 | D =

I_S, SOURCE CURRENT (A)

0

0

0.2

0.4

0.6

V_{SD}, SOURCE-DRAIN VOLTAGE (V)

Fig.8 Diode Forward Voltage vs. Current

8.0

1.0

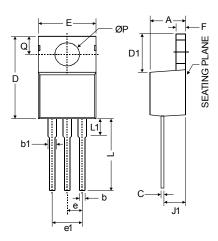
1.2

t1, PULSE DURATION TIME (sec) Fig. 10 Transient Thermal Resistance



Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



TO220-3					
Dim	Min	Max			
Α	3.55	4.85			
b	0.51	1.14			
b1	1.14	1.78			
С	0.31	1.14			
D	14.20	16.50			
D1	5.84	6.86			
Е	9.70	10.70			
е	2.79	2.99			
e1	4.83	5.33			
F	0.51	1.40			
J1	2.03	2.92			
L	12.72	14.72			
L1	3.66	6.35			
Р	3.53	4.09			
Q	2.54	3.43			
All Dimensions in mm					



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